60 V, 4.0 A, Low V_{CE(sat)} **NPN Transistor**

ON Semiconductor's e^2 PowerEdge family of low $V_{CE(sat)}$ transistors are miniature surface mount devices featuring ultra low saturation voltage (V_{CE(sat)}) and high current gain capability. These are designed for use in low voltage, high speed switching applications where affordable efficient energy control is important.

Typical applications are DC-DC converters and power management in portable and battery powered products such as cellular and cordless phones, PDAs, computers, printers, digital cameras and MP3 players. Other applications are low voltage motor controls in mass storage products such as disc drives and tape drives. In the automotive industry they can be used in air bag deployment and in the instrument cluster. The high current gain allows e²PowerEdge devices to be driven directly from PMU's control outputs, and the Linear Gain (Beta) makes them ideal components in analog amplifiers.

• These Devices are Pb-Free, Halogen Free/BFR Free and are RoHS Compliant

MAXIMUM RATINGS $(T_A = 25^{\circ}C)$

Rating	Symbol	Max	Unit
Collector-Emitter Voltage	V _{CEO}	60	Vdc
Collector-Base Voltage	V _{CBO}	140	Vdc
Emitter-Base Voltage	V _{EBO}	8.0	Vdc
Collector Current - Continuous	I _C	2.0	Α
Collector Current - Peak	I _{CM}	4.0	Α
Electrostatic Discharge	ESD	HBM Class 3B MM Class C	

THERMAL CHARACTERISTICS

Characteristic	Symbol	Max	Unit
Total Device Dissipation T _A = 25°C Derate above 25°C	P _D (Note 1)	460 3.7	mW mW/°C
20.00.0 0.00.0 0			,
Thermal Resistance, Junction-to-Ambient	R _{θJA} (Note 1)	270	°C/W
Total Device Dissipation $T_{\Delta} = 25^{\circ}C$	P _D (Note 2)	540	mW
Derate above 25°C		4.3	mW/°C
Thermal Resistance, Junction-to-Ambient	R _{θJA} (Note 2)	230	°C/W
Total Device Dissipation (Single Pulse < 10 sec.)	P _{Dsingle} (Note 3)	710	mW
Junction and Storage Temperature Range	T _J , T _{stg}	–55 to +150	°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

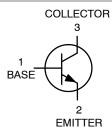
- 1. FR-4 @ 100 mm², 1 oz. copper traces. 2. FR-4 @ 500 mm², 1 oz. copper traces.
- 3. Thermal response.



ON Semiconductor®

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60 VOLTS, 4.0 AMPS NPN LOW $V_{CE(sat)}$ TRANSISTOR EQUIVALENT $R_{DS(on)}$ 70 m Ω





SOT-23 (TO-236) **CASE 318** STYLE 6

MARKING DIAGRAM



VJ = Specific Device Code

= Date Code*

= Pb-Free Package

(Note: Microdot may be in either location)

*Date Code orientation and/or overbar may vary depending upon manufacturing location.

ORDERING INFORMATION

Device	Package	Shipping [†]
NSS60201LT1G	SOT-23 (Pb-Free)	3000/Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification Brochure, BRD8011/D.

ELECTRICAL CHARACTERISTICS ($T_A = 25^{\circ}C$ unless otherwise noted)

Characteristic	Symbol	Min	Тур	Max	Unit
OFF CHARACTERISTICS			•		•
Collector – Emitter Breakdown Voltage ($I_C = 10 \text{ mAdc}, I_B = 0$)	V _(BR) CEO	60	-	-	Vdc
Collector – Base Breakdown Voltage ($I_C = 0.1 \text{ mAdc}, I_E = 0$)	V _(BR) CBO	140	-	-	Vdc
Emitter – Base Breakdown Voltage $(I_E = 0.1 \text{ mAdc}, I_C = 0)$	V _{(BR)EBO}	8.0	-	-	Vdc
Collector Cutoff Current (V _{CB} = 60 Vdc, I _E = 0)	I _{CBO}	-	-	0.1	μAdc
Emitter Cutoff Current (V _{EB} = 6.0 Vdc)	I _{EBO}	-	-	0.1	μAdc
ON CHARACTERISTICS			•		
DC Current Gain (Note 4) $(I_C = 10 \text{ mA}, V_{CE} = 2.0 \text{ V})$ $(I_C = 500 \text{ mA}, V_{CE} = 2.0 \text{ V})$ $(I_C = 1.0 \text{ A}, V_{CE} = 2.0 \text{ V})$ $(I_C = 2.0 \text{ A}, V_{CE} = 2.0 \text{ V})$	h _{FE}	160 160 150 100	- - - -	- - 350 -	
	V _{CE(sat)}	- - -	- - -	0.020 0.075 0.140	V
Base – Emitter Saturation Voltage (Note 4) $(I_C = 1.0 \text{ A}, I_B = 10 \text{ mA})$	V _{BE(sat)}	-	0.790	0.900	V
Base – Emitter Turn–on Voltage (Note 4) $(I_C = 1.0 \text{ A}, V_{CE} = 2.0 \text{ V})$	V _{BE(on)}	-	0.760	0.900	V
Cutoff Frequency (I _C = 100 mA, V _{CE} = 5.0 V, f = 100 MHz)	f _T	100	-	-	MHz
Input Capacitance (V _{EB} = 0.5 V, f = 1.0 MHz)	Cibo	-	-	380	pF
Output Capacitance (V _{CB} = 3.0 V, f = 1.0 MHz)	Cobo	_	-	45	pF
SWITCHING CHARACTERISTICS					
Delay (V_{CC} = 30 V, I_{C} = 750 mA, I_{B1} = 15 mA)	t _d	-	-	55	ns
Rise ($V_{CC} = 30 \text{ V}, I_C = 750 \text{ mA}, I_{B1} = 15 \text{ mA}$)	t _r	_	-	100	ns
Storage ($V_{CC} = 30 \text{ V}, I_{C} = 750 \text{ mA}, I_{B1} = 15 \text{ mA}$)	t _s	-	-	1100	ns
Fall (V _{CC} = 30 V, I _C = 750 mA, I _{B1} = 15 mA)	t _f	_	-	120	ns

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

4. Pulsed Condition: Pulse Width = 300 msec, Duty Cycle ≤ 2%.

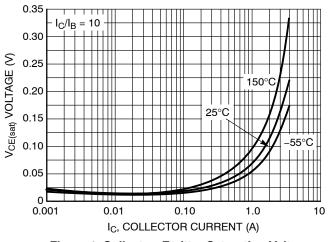


Figure 1. Collector-Emitter Saturation Voltage

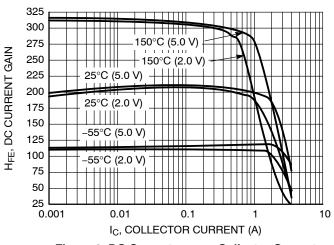


Figure 2. DC Current versus Collector Current

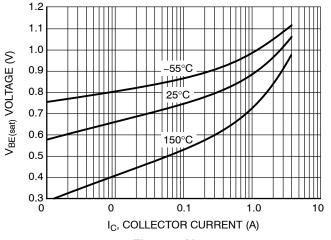


Figure 3. V_{BE(sat)}

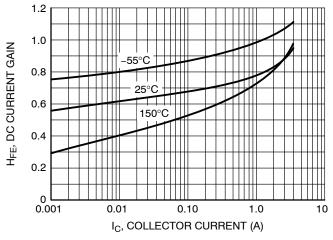
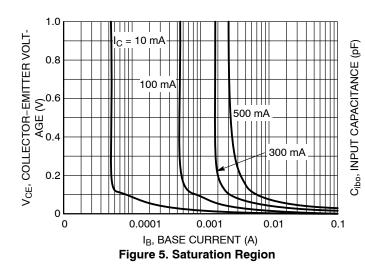


Figure 4. V_{BE(on)}



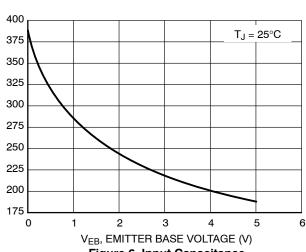


Figure 6. Input Capacitance

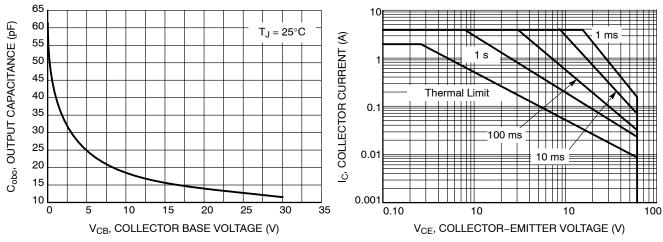
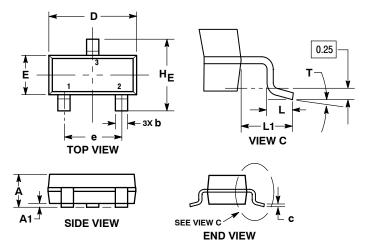


Figure 7. Output Capacitance

Figure 8. Safe Operating Area Single Pulse Test @ T_{amb} = 25°C

PACKAGE DIMENSIONS

SOT-23 (TO-236) CASE 318-08 ISSUF AR



NOTES:

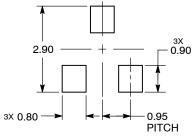
- DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994. CONTROLLING DIMENSION: MILLIMETERS. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF THE BASE MATERIAL.
- DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS.

	MILLIMETERS			INCHES		
DIM	MIN	NOM	MAX	MIN	NOM	MAX
Α	0.89	1.00	1.11	0.035	0.039	0.044
A1	0.01	0.06	0.10	0.000	0.002	0.004
b	0.37	0.44	0.50	0.015	0.017	0.020
С	0.08	0.14	0.20	0.003	0.006	0.008
D	2.80	2.90	3.04	0.110	0.114	0.120
E	1.20	1.30	1.40	0.047	0.051	0.055
е	1.78	1.90	2.04	0.070	0.075	0.080
L	0.30	0.43	0.55	0.012	0.017	0.022
L1	0.35	0.54	0.69	0.014	0.021	0.027
HE	2.10	2.40	2.64	0.083	0.094	0.104
Т	0°		10 °	0 °		10 °

STYLE 6: PIN 1. BASE

EMITTER 2. COLLECTOR

RECOMMENDED SOLDERING FOOTPRINT*



DIMENSIONS: MILLIMETERS

*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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